

VERSION WITH MARKINGS SHOWING CHANGES MADEIN THE SPECIFICATION:

After the title and before the first paragraph:

THIS APPLICATION IS A U.S. NATIONAL PHASE
APPLICATION OF PCT INTERNATIONAL APPLICATION
PCT/JP01/05201.

Specification at page 5, line 1:

~~The 1st invention~~ One aspect of the present invention
(~~corresponding to claim 1~~) is a laminated bandpass filter comprising:

Specification at page 5, line 24:

~~The 2nd invention~~ Another aspect of the present invention
(~~corresponding to claim 2~~) is the laminated bandpass filter ~~according to the 1st~~
~~invention~~, wherein said first and second strip lines have the same length and
width.

Specification at page 6, line 3:

~~The 3rd invention~~ Still another aspect of the present invention
(~~corresponding to claim 3~~) is the laminated bandpass filter ~~according to the 1st~~
~~or 2nd invention~~, wherein said first and second strip lines are placed in parallel
with each other.

Specification at page 6, line 8:

~~The 4th invention~~ Yet still another aspect of the present invention
(~~corresponding to claim 4~~) is the laminated bandpass filter ~~according to any~~

~~one of the 1st to 3rd inventions~~, wherein said first and second strip lines are electrically connected to said internal grounding electrode via a via hole.

Specification at page 6, line 14:

~~The 5th invention~~ Still yet another aspect of the present invention ~~(corresponding to claim 5)~~ is the laminated bandpass filter ~~according to any one of 1st to 4th inventions~~, wherein only said first and second strip lines are placed on said dielectric sheet.

Specification at page 6, line 19:

~~The 6th invention~~ A further aspect of the present invention ~~(corresponding to claim 6)~~ is a laminated bandpass filter comprising:

Specification at page 7, line 21:

~~The 7th invention~~ A still further aspect of the present invention ~~(corresponding to claim 7)~~ is the laminated bandpass filter ~~according to the 6th invention~~, wherein said first and second strip lines have the same length, width and position within the plane.

Specification at page 8, line 1:

~~The 8th invention~~ A yet further aspect of the present invention ~~(corresponding to claim 8)~~ is the laminated bandpass filter ~~according to the 6th or 7th invention~~, wherein said first and second strip lines are electrically connected to said internal grounding electrode via a via hole.

Specification at page 8, line 7:

~~The 9th invention~~ A still yet further aspect of the present

invention (~~corresponding to claim 9~~) is the laminated bandpass filter ~~according to any one of the 1st to 8th inventions~~, further comprising:

Specification at page 8, line 23:

~~The 10th invention~~ An additional aspect of the present invention (~~corresponding to claim 10~~) is the laminated bandpass filter ~~according to any one of the 1st to 9th invention~~, wherein capacitive coupling of an area where said fourth capacitor electrode and said fifth capacitor electrode overlap each other in the lamination direction forms a jump capacitance.

Specification at page 9, line 5:

~~The 11th invention~~ A still additional aspect of the present invention (~~corresponding to claim 11~~) is the laminated bandpass filter ~~according to any one of the 1st to 10th invention~~, wherein with respect to said grounding electrode, an electrode pattern of at least one of said first and second capacitor electrodes is laminated, an electrode pattern of at least one of said first and second strip lines is laminated on a layer superior thereto, and an electrode pattern of at least one of the capacitor electrode connected to said input electrode and the capacitor electrode connected to said output electrode is laminated on a layer superior to said layer.

Specification at page 9, line 17:

~~The 12th invention~~ A yet additional aspect of the present invention (~~corresponding to claim 12~~) is the laminated bandpass filter ~~according to any one of the 1st to 10th inventions~~, wherein all electrode patterns constituting the capacitor electrode connected to said input electrode and the capacitor electrode connected to said output electrode as an

input/output capacitance are provided on a layer superior to the layer constituting said strip lines.

Specification at page 10, line 1:

~~The 13th invention~~ A still yet additional aspect of the present invention is the laminated bandpass filter according to the 9th invention, wherein with respect to said grounding electrode, an electrode pattern of at least one of said first and second capacitor electrodes is laminated, an electrode pattern of at least one of said first and second strip lines is laminated on a layer superior thereto, and an electrode pattern of at least one of said third to sixth capacitor electrodes is laminated on a layer superior to said layer.

Specification at page 10, line 10:

~~The 14th invention~~ A supplementary aspect of the present invention (corresponding to claim 14) is the laminated bandpass filter ~~according to the 9th invention,~~ wherein said third to sixth capacitor electrodes are provided on a layer superior to the layer constituting said strip lines.

Specification at page 10, line 15:

~~The 15th invention~~ A still supplementary aspect of the present invention (corresponding to claim 15) is a laminated bandpass filter comprising:

Specification at page 11, line 21:

~~The 16th invention~~ A yet supplementary aspect of the present invention (corresponding to claim 16) is the laminated bandpass filter ~~according to the 15th invention,~~ wherein said first to fourth strip lines have the

same length and width, said first and third strip lines have the same position within the plane and said second and fourth strip lines have the same position within the plane.

Specification at page 12, line 3:

~~The 17th invention~~ A still yet supplementary aspect of the present invention (corresponding to claim 17) is the laminated bandpass filter ~~according to the 15th or 16th invention~~, wherein said first and second strip lines are placed in parallel with each other and said third and fourth strip lines are placed in parallel with each other.

Specification at page 12, line 9:

~~The 18th invention~~ Another aspect of the present invention (corresponding to claim 18) is the laminated bandpass filter ~~according to any one of the 15th to 17th inventions~~, wherein said first to fourth strip lines are connected to said internal grounding electrode via a via hole.

Specification at page 12, line 14:

~~The 19th invention~~ Still another aspect of the present invention (corresponding to claim 19) is the laminated bandpass filter ~~according to any one of the 15th to 18th inventions~~, further comprising:

Specification at page 13, line 5:

~~The 20th invention~~ Yet still another aspect of the present invention (corresponding to claim 20) is the laminated bandpass filter ~~according to any one of the 15th to 19th inventions~~, wherein capacitive coupling of an area where said sixth capacitor electrode and said seventh

capacitor electrode overlap each other in the lamination direction forms a jump capacitance.

Specification at page 13, line 12:

~~The 21st invention~~ Still yet another aspect of the present invention (~~corresponding to claim 21~~) is the laminated bandpass filter ~~according to any one of the 1st to the 20th inventions~~, wherein said dielectric sheet is made up of a crystal phase and a glass phase, said crystal phase includes at least one of Al_2O_3 , MgO , SiO_3 and RO_a where R is at least one element selected from La, Ce, Pr, Nd, Sm and Gd and a is a numerical value determined stoichiometrically according to the valence of said R.

Specification at page 13, line 21:

~~The 22nd invention~~ A further aspect of the present invention (~~corresponding to claim 22~~) is a laminated bandpass filter, said laminated body incorporating the bandpass filter ~~according to any one of the 1st to 21st inventions~~ and the bandpass filter ~~according to any one of the 1st to 21st inventions~~.

Specification at page 14, line 3:

~~The 23rd invention~~ A still further aspect of the present invention (~~corresponding to claim 23~~) is a composite high frequency device, wherein said laminated body incorporates the bandpass filter ~~according to any one of the 1st to the 21st inventions~~ and another high frequency circuit.

Specification at page 14, line 8:

~~The 24th invention~~ A yet further aspect of the present invention

~~(corresponding to claim 24)~~ is a composite high frequency device, wherein electronic parts are mounted on said laminated body incorporating the bandpass filter ~~according to any one of the 1st to 21st inventions.~~

Specification at page 14, line 13:

~~The 25th invention~~ A still yet further aspect of the present invention ~~(corresponding to claim 25)~~ is a high frequency device, characterized by comprising the laminated bandpass filter ~~according to any one of the 1st to 24th inventions.~~

Specification at page 14, line 17:

~~The 26th invention~~ An additional aspect of the present invention ~~(corresponding to claim 26)~~ is a laminated bandpass filter manufacturing method comprising the steps of:

Specification at page 15, line 16:

~~The 27th invention~~ A still additional aspect of the present invention ~~(corresponding to claim 27)~~ is a laminated bandpass filter manufacturing method comprising the steps of:

Specification at page 16, line 20:

~~The 28th invention~~ A yet additional aspect of the present invention ~~(corresponding to claim 28)~~ is a laminated bandpass filter manufacturing method comprising the steps of:

Specification at page 29, line 19:

Furthermore, the dielectric layer 505 has strip lines 520 and 521,

and the dielectric layer 506 has strip lines 522 and 523. The dielectric layer 507 has capacitor electrodes 524 and 525 and the dielectric layer ~~507~~ 508 has an internal grounding electrode 526 and connected to the grounding electrode 510.

Specification at page 34, line 21:

The capacitor electrode 916 is connected to one end ~~914a~~ 915a of the strip line ~~914~~ 915 and the capacitor electrode 912 via a via hole 920 and the capacitor electrode 917 is connected to one end ~~915a~~ 914a of the strip line ~~915~~ 914 and the capacitor electrode 913 via a via hole 921.

IN THE CLAIMS:

4. (Amended) The laminated bandpass filter according to ~~any one of claims 1 to claim 3~~ or 2, wherein said first and second strip lines are electrically connected to said internal grounding electrode via a via hole.

5. (Amended) The laminated bandpass filter according to ~~any one of claims 1 to claim 4~~ or 2, wherein only said first and second strip lines are placed on said dielectric sheet.

9. (Amended) The laminated bandpass filter according to any one of claims 1, 2, 3, 4, 5, 6 or 7, further comprising:

a third capacitor electrode connected to said input electrode;

a fourth capacitor electrode connected to said output electrode;

a fifth capacitor electrode capacitatively coupled with said third

capacitor electrode; and

a sixth capacitor electrode capacitatively coupled with said fourth capacitor electrode,

wherein capacitive coupling of an area where said third capacitor electrode and said sixth capacitor electrode overlap each other in the lamination direction forms a jump capacitance.

10. (Amended) The laminated bandpass filter according to any one of claims 1, ~~to claim 9~~2, 6 or 7, wherein capacitive coupling of an area where said fourth capacitor electrode and said fifth capacitor electrode overlap each other in the lamination direction forms a jump capacitance.

11. (Twice Amended) The laminated bandpass filter according to any one of claims 1, ~~to claim 8~~2, 6 or 7, wherein with respect to said internal grounding electrode, on a layer superior thereto, an electrode pattern of at least one of said first and second capacitor electrodes is laminated, an electrode pattern of at least one of said first and second strip lines is laminated on a layer superior thereto, and an electrode pattern of at least one of the capacitor electrode connected to said input electrode and the capacitor electrode connected to said output electrode is laminated on a layer superior to said layer.

12. (Twice Amended) The laminated bandpass filter according to any one of claims 1, ~~to claim 8~~2, 6 or 7, wherein all electrode patterns constituting the capacitor electrode connected to said input electrode, the capacitor electrode connected to said output electrode and an input/output capacitance are provided on a layer superior to the layer constituting said strip

lines.

13. (Twice Amended) The laminated bandpass filter according to claim ~~9 or 10~~, wherein with respect to said internal grounding electrode, on a layer superior thereto, an electrode pattern of at least one of said first and second capacitor electrodes is laminated, an electrode pattern of at least one of said first and second strip lines is laminated on a layer superior thereto, and an electrode pattern of at least one of said third to sixth capacitor electrodes is laminated on a layer superior to said layer.

14. (Twice Amended) The laminated bandpass filter according to claim ~~9 or 10~~, wherein said all of third to sixth capacitor electrodes are provided on a layer superior to the layer constituting said strip lines.

18. (Amended) The laminated bandpass filter according to ~~any one of claims 15 to claim 17~~ or 16, wherein said first to fourth strip lines are connected to said internal grounding electrode via a via hole.

19. (Twice Amended) The laminated bandpass filter according to ~~any one of claims 15 to claim 18~~ or 16, further comprising:

a fifth capacitor electrode connected to said input electrode;

a sixth capacitor electrode connected to said output electrode;

a seventh capacitor electrode capacitatively coupled with said fifth capacitor electrode; and

an eighth capacitor electrode capacitatively coupled with said sixth capacitor electrode,

wherein capacitive coupling of an area where said fifth capacitor electrode and said eighth capacitor electrode overlap each other in the lamination direction forms a jump capacitance.

20. (Amended) The laminated bandpass filter according to ~~any one of claims 15 to claim 19~~ or 16, wherein capacitive coupling of an area where said sixth capacitor electrode and said seventh capacitor electrode overlap each other in the lamination direction forms a jump capacitance.

Claim 21 has been cancelled.

22. (Twice Amended) A composite high frequency device, wherein said laminated body incorporates the bandpass filter according to any one of claims 1, to claim 20, 6, 7, 15 or 16 and another high frequency circuit.

23. (Twice Amended) A composite high frequency device, wherein electronic parts are mounted on said laminated body incorporating the bandpass filter according to any one of claims 1, to claim 20, 6, 7, 15 or 16.

24. (Twice Amended) The laminated bandpass filter according to any one of claims 1, to claim 23, 6, 7, 15 or 16, wherein said dielectric sheet is made up of a crystal phase and a glass phase, said crystal phase includes at least one of Al_2O_3 , MgO , SiO_3 and RO_a where R is at least one element selected from La, Ce, Pr, Nd, Sm and Gd and a is a numerical value determined stoichiometrically according to the valence of said R.

25. (Amended) A high frequency device, characterized by comprising the laminated bandpass filter according to any one of claims 1, to claim 24, 6, 7, 15 or 16.